

# Golden List of Reviewers for 2023

First Name	Last Name	Affiliation	Country
Abdollah	Abbasi	Semnan University	Iran
Mohamed	Abouelatta	Ain Shams University	Egypt
Ahmad	Abushattal	University of Santiago de Compostela	Spain
Fabio	Acerbi	Fondazione Bruno Kessler	Italy
Rachana	Acharya	University of Cambridge	United Kingdom
Abhisekh	Acharya	SVNIT Surat	India
Eliana	Acurio	Universita degli Studi della Calabria	Italy
Fikru	Adamu-Lema	University of Glasgow	United Kingdom
Manoj	Adhikari	G B Pant Engineering College Pauri	India
Sheel	Aditya	Nanyang Technological University	Singapore
Aryan	Afzalian	IMEC	Belgium
Anant	Agarwal	The Ohio State University	United States
Harshit	Agarwal	Indian Institute of Technology Jodhpur	India
Lucky	Agarwal	Madanapalle Institute of Technology and Science	India
Rajesh	Agarwal	SRM University	India
Paula	Agopian	Sao Paulo State University	Brazil
Jitesh	Agrawal	Indian Institute of Technology Indore	India
Karim	Ahmed	National University of Singapore	Singapore
Phil-Hun	Ahn	Gwangju Institute of Science and Technology	South Korea
Seung	Ahn	Tech University of Korea	South Korea
Shinya	Aikawa	Kogakuin University	Japan
Arjun	Ajaykumar	IMEC	Belgium
Akintunde Ibitayo (Tayo)	Akinwande	Massachusetts Institute of Technology	United States
Ozgur	Aktas	Avogy	United States
Akin	Akturk	CoolCAD Electronics	United States
Arsalan	Alam	University of California, Los Angeles	United States
Monzurul	Alam	North Carolina Agricultural and Technical State University	United States
Muhammad A.	Alam	Purdue University	United States
Mukesh	Alaria	CEERI Pilani	India
Matteo	Alasio	Politecnico di Torino	Italy
Sayed	Albahrani	Fraunhofer IAF	Germany
Martino	Aldrigo	Institutul National de Cercetare Dezvoltare Pentru Microtehnologie	Romania
Bilawal	Ali	University of Electronic Science and Technology of China	China
Washim	Ali	National Tsing Hua University	Taiwan
Gazmend	Alia	Infineon Technologies AG	Germany
Şemsettin	Altundal	Gazi University	Turkey
Rakesh	Aluguri	National Chiao Tung University	Taiwan
Mehadi	Aman	Sharp Corp Tenri	Japan
Esteve	Amat	IMB CNM	Spain
Stefano	Ambrogio	IBM Almaden Research Center	United States
Elia	Ambrosi	Taiwan Semiconductor Manufacturing Co Ltd	Taiwan
Tarek	Ameen	Purdue University	United States
S.	Amin	Jamia Millia Islamia	India
Salvatore	Amoroso	Synopsys Inc.	United Kingdom
Hussam	Amrouch	University of Stuttgart	Germany

<b>First Name</b>	<b>Last Name</b>	<b>Affiliation</b>	<b>Country</b>
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Mario	Ancona	Florida State University	United States
Yuji	Ando	Nagoya University	Japan
Frédéric	André	Thales Electron Devices	France
Andrey	Andreev	The University of New Mexico	United States
Francois	Andrieu	CEA-LETI	France
Diing Shenp	Ang	Nanyang Technological University	Singapore
Lay-Kee Ricky	Ang	Singapore University of Technology and Design	Singapore
Yee Sin	Ang	Singapore University of Technology and Design	Singapore
Sergio	Anza	Dassault Systemes	Spain
Jin-Ping	Ao	Jiangnan University	China
Daisuke	Arai	Nagoya University	Japan
Salman	Arain	NFC Institute of Engineering and Fertilizer Research	Pakistan
Yuri	Ardesi	Politecnico di Torino	Italy
Bertrand	Ardouin	III-V Lab	France
Mehmet	Arık	Auburn University	United States
Martin	Arnold	Cambridge GaN Devices	United Kingdom
Monika	Arora	Everspin Technologies Inc	United States
Daniel	Arumi	Universitat Politècnica de Catalunya	Spain
Reza	Asadpour	Purdue University	United States
Tanemasa	Asano	Kyushu University	Japan
Ruben	Asanovski	Università degli Studi di Modena e Reggio Emilia	Italy
Shiva	Asapu	University of Massachusetts Amherst	United States
Joel	Asubar	University of Fukui	Japan
Fabia Farlin	Athena	Georgia Institute of Technology	United States
Victor	Atuchin	Institut fiziki poluprovodnikov imeni A V Rzanova SO RAN	Russia
Matthias	Auf der Maur	University of Rome "Tor Vergata"	Italy
Klaus	Aufinger	Infineon Technologies AG	Germany
Konstantinos	Avramidis	National and Kapodistrian University of Athens	Greece
Eugene	Avrutin	University of York	United Kingdom
Neslihan	Ayarcı Kuruoğlu	Yildiz Technical University	Turkey
Mohammad	Azarifar	Auburn University	United States
Ahmedullah	Aziz	University of Tennessee Knoxville	United States
Akbar	Babaeihasehghobi	Sahand University of Technology	Iran
Jeff	Babcock	Texas Instruments Inc	United States
Naveen	Babu	Shiv Nadar University	India
Giorgio	Baccarani	University of Bologna	Italy
Oves	Badami	Indian Institute of Technology Hyderabad	India
Jong-Uk	Bae	LG Display	South Korea
Kang-Jun	Baeg	Pukyong National University	South Korea
Chang-Ki	Baek	POSTECH	South Korea
Rock-Hyun	Baek	POSTECH	South Korea
Marta	Bagatin	University of Padova	Italy
Navjeet	Bagga	Indian Institute of Technology Bhubaneswar	India
Mehdi	Bagheri	Nazarbayev University	Kazakhstan
Eldad	Bahat Treidel	Ferdinand-Braun-Institut für Höchstfrequenztechnik	Germany
Sandeep	Bahl	Texas Instruments Inc	United States
Ningfeng	Bai	Southeast University	China
Benoit	Bakeroot	IMEC	Belgium
Yashwanth	Balaji	IMEC	Belgium
Mannix	Balanay	Nazarbayev University	Kazakhstan
Krishna	Balasubramanian	Indian Institute of Technology Delhi	India
Matteo	Baldo	Politecnico di Milano	Italy
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Abhishek	Banerjee	BelGaN	Belgium
Abhishek	Banerjee	ON Semiconductor	Belgium
Writam	Banerjee	Pohang University of Science and Technology	South Korea
Anil Kumar	Bansal	Intel Corporation	United States
Ashok	Bansiwal	DRDO Microwave Tube Research and Development Center	India
Hua	Bao	Shanghai Jiao Tong University	China
Xinyu	Bao	Taiwan Semiconductor Manufacturing Co Ltd	Taiwan
Marinela	Barci	Huawei Technologies R&D Belgium NV	Belgium
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Baidyanath	Basu	College of Engineering & Technology	India
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Rupa	Basu	Lancaster University	United Kingdom
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Thomas	Bédécarrats	CEA-LETI	France
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Alessandro	Bellucci	IMIP-CNR	Italy
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Daniel	Benedikovic	University of Zilina	Slovakia
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Zhengliang	Bian	Stanford University	United States
Namita	Bindal	Indian Institute of Technology Roorkee	India
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Phillipp	Borchard	Dymenso LLC	United States
Matteo	Borga	IMEC	Belgium
Gianluca	Boselli	Texas Instruments Inc.	United States
Thiago	Both	NXP Semiconductors	Netherlands
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Peter	Brückner	Fraunhofer IAF	Germany
Dan	Buca	Forschungszentrum Jülich GmbH	Germany
Matthias	Bucher	Technical University of Crete	Greece
Fabian	Bufler	IMEC	Belgium
Graeme	Burt	Lancaster University	United Kingdom
Jialin	Cai	Hangzhou Dianzi University	China
Jinchi	Cai	University of Electronic Science and Technology of China	China
Jun	Cai	Beijing Vacuum Electronics Research Institute	China
Mengye	Cai	The University of British Columbia	Canada
Puyang	Cai	Peking University	China
Yimao	Cai	Peking University	China
Yong	Cai	Chinese Academy of Sciences	China
Jeffrey	Calame	Naval Research Laboratory	United States
Francis	Calmon	Université de Lyon	France
Laurie E	Calvet	Universite Paris Sud - Paris 11	France
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Giuseppe	Cantarella	Libera Università di Bolzano	Italy
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Chen	Cao	Shizuoka University	Japan
Hongtao	Cao	Ningbo Institute of Materials Technology and Engineering Chinese Academy of Sciences	China
Jiang	Cao	ETH Zürich	Switzerland
Wei	Cao	University of California at Santa Barbara	United States
Yu	Cao	Arizona State University	United States
Filippo	Capolino	University of California Irvine	United States
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Bruna	Cardoso Paz	Institut NÉEL	France
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Mikael	Casse	CEA Grenoble	France
Stephen	Cauffman	CPI International, Inc.	United States
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Didier	Celi	STMicroelectronics	France
Rene	Celis	University of Notre Dame	United States
Lorenzo	Cerati	STMicroelectronics SRL Sede di Agrate Brianza	Italy
Antonio	Cerdeira	CINVESTAV	Mexico
Hajdin	Ceric	TU Vienna	Austria
Ho-Young	Cha	Hongik University	South Korea
V. R. Saran Kumar	Chaganti	Intel Corporation	United States
Junshuai	Chai	Institute of Microelectronics, Chinese Academy of Sciences	China
Yang	Chai	Hong Kong Polytechnic University	Hong Kong
Zheng	Chai	Xi'an Jiaotong University	China
Wriddhi	Chakraborty	Intel Ronler Acres Campus	United States
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First Name	Last Name	Affiliation	Country
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Hsiang-Hung	Chang	ITRI	Taiwan
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Pengying	Chang	Beijing University of Technology	China
Peng-Ying	Chang	Peking University	China
Ruey-Dar	Chang	Chang Gung University	Taiwan
Sheng	Chang	Wuhan University	China
Sheng-Po	Chang	National Kaohsiung University of Science and Technology	Taiwan
Sou-Chi	Chang	Georgia Institute of Technology	United States
Ting-Chang	Chang	National Sun Yat-Sen University	Taiwan
Wen Hsin	Chang	National Institute of Advanced Industrial Science and Technology	Japan
Wen-Teng	Chang	National University of Kaohsiung	Taiwan
Yao-Feng	Chang	Intel Corporation	United States
Yao-Wen	Chang	Macronix International Co. Ltd.	Taiwan
Zhiwei	Chang	University of Electronic Science and Technology of China	China
Kuei-Shu	Chang-Liao	National Tsing Hua University	Taiwan
Hsueh-Yung	Chao	ANSYS Inc	United States
Tien-Sheng	Chao	National Chiao Tung University	Taiwan
Adam	Charnas	Air Force Research Laboratory	United States
Bikramjit	Chatterjee	Lawrence Livermore National Laboratory	United States
Indranil	Chatterjee	Airbus Defence and Space GmbH Immenstaad	Germany
Korok	Chatterjee	University of California, Berkeley	United States
Neel	Chatterjee	University of Minnesota Twin Cities	United States
Sulagna	Chatterjee	University of Calcutta	India
Swetaki	Chatterjee	Indian Institute of Technology Kanpur	India
Rishu	Chaujar	Delhi Technological University	India
Bharani	Chava	Qualcomm Technologies Inc.	United States
Bilal	Chehab	IMEC	Belgium
Ioannis	Chelis	National and Kapodistrian University of Athens	Greece
An	Chen	IBM Research	United States
Bing	Chen	Zhejiang University	China
Chih-Kuang	Chen	National Sun Yat-Sen University	Taiwan
Chin-Yi	Chen	Purdue University	United States
Chi-Wen	Chen	Solomon Systech Ltd	Taiwan
Dekang	Chen	Intel Corporation	United States
DeYang	Chen	South China University of Technology	China
Dunjun	Chen	Nanjing University	China
Enguo	Chen	Fuzhou University	China
Huiling	Chen	Wenzhou University	China
Huipeng	Chen	Fuzhou University	China
Jiezhi	Chen	Shandong University	China
Jr-Tai	Chen	SweGaN AB	Sweden
Jun	Chen	Sun Yat-Sen University	China
Junting	Chen	The Hong Kong University of Science and Technology	Hong Kong
Miin-Jang	Chen	National Taiwan University	Taiwan
Po	Chen	University of California San Diego	United States
Qi	Chen	University of California Riverside	United States
Quan	Chen	University of Hong Kong	Hong Kong
Rongsheng	Chen	South China University of Technology	China
Ruo-Si	Chen	Shenzhen University	China
Shi	Chen	Huazhong University of Science and Technology	China
Shih-Hung	Chen	IMEC	Belgium
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First Name	Last Name	Affiliation	Country
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Wenchao	Chen	Zhejiang University	China
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Yangyin	Chen	IMEC/SanDisk	Belgium
Yongsheng	Chen	Zhengzhou University	China
Zhao	Chen	Nanjing University of Information Science and Technology	China
Zhigang	Chen	Queensland University of Technology	Australia
Zhizhong	Chen	Purdue University	United States
Zhong	Chen	University of Arkansas	United States
Binjie	Cheng	Synopsys Inc.	United Kingdom
Chun-Hu	Cheng	National Taiwan Normal University	Taiwan
Junao	Cheng	Texas Instruments Inc	United States
Qiang	Cheng	Huazhong University of Science and Technology	China
Ran	Cheng	Zhejiang University	China
Xu	Cheng	NXP Semiconductors	United States
Zhenzhou	Cheng	Tianjin University	China
Zhihui	Cheng	Duke University	United States
Anna G.	Chernikova	Moscow Institute of Physics and Technology	Russia
David	Chernin	Science Applications International Corp.	United States
Igor	Chernyavskiy	Naval Research Laboratory	United States
Pascal	Chevalier	STMicroelectronics	France
Meng-Hsueh	Chiang	National Cheng Kung University	Taiwan
Chao-Hsin	Chien	National Yang Ming Chiao Tung University	Taiwan
Wei-Chih	Chien	Macronix International Co. Ltd.	Taiwan
Alessandro	Chini	University of Modena and Reggio Emilia	Italy
Hsien-Chin	Chiu	Chang Gung University	Taiwan
Yung-Yueh	Chiu	National Chiao Tung University	Taiwan
Il Hwan	Cho	Myongji University	South Korea
Jungwan	Cho	Sung Kyun Kwan University	South Korea
Seongjae	Cho	Ewha Womans University	South Korea
Sung Haeng	Cho	Electronics and Telecommunication Research Institute	South Korea
Byong-Deok	Choi	Hanyang University	South Korea
Heungjae	Choi	Cardiff University	United Kingdom
Hyejeong	Choi	Yonsei University	South Korea
Jaehyuk	Choi	Sung Kyun Kwan University	South Korea
Jin Joo	Choi	Kwangwoon University	South Korea
Pyeong Hwi	Choi	Gwangju Institute of Science and Technology	South Korea
Rino	Choi	Inha University	South Korea
Wooseok	Choi	Pohang University of Science and Technology	South Korea
Yoon Seuk Choi	Choi	Hanbat National University	South Korea
Bijit	Choudhuri	National Institute of Technology Silchar	India
Rihab	Chouk	University of Monastir	Tunisia
Anastasia	Chouprik	Moscow Institute of Physics and Technology	Russia
Chi-Wai	Chow	National Yang Ming Chiao Tung University	Taiwan
T. Paul	Chow	Rensselaer Polytechnic Institute	United States
Nadim	Chowdhury	Massachusetts Institute of Technology	United States
Sauvik	Chowdhury	ON Semiconductor	United States
Latha	Christie	Microwave Tube Research & Development Centre	India
Rongming	Chu	Pennsylvania State University	United States
Yuanchen	Chu	Massachusetts Institute of Technology	United States
Kai-Hsin	Chuang	PUFsecurity Inc.	Taiwan
Peng	Cong	Case Western Reserve University	United States
Alan	Cook	Naval Research Laboratory	United States
Simon	Cooke	Naval Research Laboratory	United States
Yvon	Cordier	CNRS	France
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First Name	Last Name	Affiliation	Country
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Angela	Coves	Universidad Miguel Hernández de Elche	Spain
Erika	Covi	NaMLab gGmbH	Germany
Sorin	Cristoloveanu	IMEP-LAHC	France
Kristof	Croes	IMEC	Belgium
Matteo	Cucchi	École polytechnique fédérale de Lausanne (EPFL)	Switzerland
Xiaole	Cui	Peking University	China
Yumeng	Cui	Texas Instruments Inc	United States
Zhixin	Cui	Western Digital Technologies Inc	United States
A.	Cutivet	Universite de Sherbrooke	Canada
Chetan	Dabhi	University of California Berkeley	United States
Qing	Dai	National Center for Nanoscience & Technology	China
Gian-Franco	Dalla Betta	University of Trento	Italy
Joseph	D'Amico	Vanderbilt University	United States
Michael	Dammann	Fraunhofer IAF	Germany
Flavio Santos	Damos	Universidade Federal do Maranhão	Brazil
Yaping	Dan	Shanghai Jiao Tong University	China
Raghvendra	Dangi	Indian Institute of Technology Kanpur	India
Francois	Danneville	IEMN UMR CNRS	France
Debasis	Das	National University of Singapore	Singapore
Mukul Kumar	Das	IITISM	India
Partha	Das	National Institute of Technology Durgapur	India
Pritam	Das	Binghamton University	United States
Samaresh	Das	Indian Institute of Technology Delhi	India
Saptarshi	Das	Pennsylvania State University	United States
Uttam	Das	King Abdullah University of Science and Technology	Saudi Arabia
Amitava	DasGupta	Indian Institute of Technology Madras	India
Avirup	Dasgupta	Indian Institute of Technology Roorkee	India
Nandita	DasGupta	Indian Institute of Technology Madras	India
Sudeb	Dasgupta	Indian Institute of Technology Roorkee	India
Tarapasanna	Dash	ITER, SOA University	India
Subrata Kumar	Datta	DRDO Microwave Tube Research and Development Center	India
John	David	University of Sheffield	United Kingdom
Jonathan	Davidson	University of Sheffield	United Kingdom
Mary	De Feudis	CY Cergy Paris Université	France
Gijs	de Raad	NXP Semiconductors	Netherlands
Carlo	De Santi	University of Padova	Italy
Michelly	de Souza	Centro Universitário da FEI	Brazil
William	Deal	Northrop Grumman Corporation	United States
Ahmet	Demirkol	TU Dresden	Germany
Marina	Deng	University of Bordeaux	France
Wanling	Deng	College of Information Science and Technology	China
Xiangying	Deng	Western Digital Technologies Inc	United States
Xiaochuan	Deng	University of Electronic Science and Technology of China	China
Yuan	Deng	Beihang University	China
Eugenio	Dentoni Litta	IMEC	Belgium
Theeradetch	Detchprohm	Georgia Institute of Technology	United States
Amos	Dexter	Lancaster University	United Kingdom
Sukomal	Dey	Indian Institute of Technology Palakkad	India
Siva	Dhanuskodi	University of Massachusetts Amherst	United States
Sarit	Dhar	Auburn University	United States
Siddhartha	Dhar	STMicroelectronics	France
Mahesh	Dhonde	Govt. Model Autonomous Holkar Science College	India
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Antonio	Di Bartolomeo	University of Salerno	Italy
Luigi	Di Benedetto	University of Salerno	Italy
Bernard	Dieny	SPINTEC	France
Surya	Dikshit	Indian Institute of Technology Roorkee	India
Charalabos	Dimitriadis	Aristotle University of Thessaloniki	Greece
Sima	Dimitrijevic	Griffith University	Australia
A. Thanasis	Dimoulas	NCSR Demokritos	Greece
Haibing	Ding	Chinese Academy of Sciences	China
Shi-Jin	Ding	Fudan University	China
Xinrui	Ding	South China University of Technology	China
Thanh Viet	Dinh	NXP Semiconductors Belgium	Belgium
Toan	Dinh	Griffith University	Australia
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Bruno	Dlubak	Unité Mixte de Physique CNRS	France
Philippe	Dollfus	CNRS	France
Craig	Donaldson	University of Strathclyde	United Kingdom
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Simona	Donati-Guerrieri	Politecnico di Torino	Italy
Nazareno	Donato	University of Cambridge	United Kingdom
Luca	Donetti	Universidad of Granada	Spain
Changkun	Dong	Wenzhou University	China
Chengyuan	Dong	Shanghai Jiao Tong University	China
Shurong	Dong	Zhejiang University	China
Ye	Dong	Institute of Applied Physics and Computational Mathematics	China
Zhipeng	Dong	University of Florida	United States
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Rodrigo	Doria	Centro Universitário da FEI	Brazil
Richard	Dorrance	Intel Corp Hillsboro	United States
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Rachid	Driad	Fraunhofer IAF	Germany
Francesco	Driussi	Universita Degli Studi Di Udine	Italy
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Fengyu	Du	Xidian University	China
Liqun	Du	Dalian University of Technology	China
Baoxing	Duan	Xidian University	China
Lian	Duan	Tsinghua University	China
Meng	Duan	Synopsys Inc.	United Kingdom
Yu	Duan	University of Notre Dame	United States
Zhaoyun	Duan	University of Electronic Science and Technology of China	China
Prabhat	Dubey	Indian Institute of Technology Roorkee	India
Fabian	Ducry	ETH Zürich D-ITET	Switzerland
Stefan	Dünkel	GlobalFoundries	Germany
The	Duong	Australian National University	Australia
Aloke	Dutta	IIT Kanpur	India
Anupam	Dutta	GlobalFoundries	India
Tapas	Dutta	University of Glasgow	United Kingdom
Sayak	Dutta Gupta	Indian Institute of Science	India
Anurag	Dwivedi	Indian Institute of Technology Jodhpur	India
Smrity	Dwivedi	Indian Institute of Technology (BHU)	India
Abdalla	Eblabla	Cardiff University	United Kingdom
Loizos	Efthymiou	University of Cambridge	United Kingdom
Robert	Elliman	Australian National University	Australia
Jimmy	Encomendero	Cornell University	United States
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Agah	Ertay	Erzincan University	Turkey
Selva	Esakki	Sri Paramakalyani College	India
Jason	Eshraghian	University of California Santa Cruz	United States
Mohammad	Esmaeildoust	Khorramshahr Marine Science and Technology University	Iran
David	Esseni	University of Udine	Italy
Magali	Estrada	Centro de Investigacion y de Estudios Avanzados del Instituto Politecnico Nacional	Mexico
Magali	Estribeau	ISAE-SUPAERO	France
Ching-Lin	Fan	National Taiwan University of Science and Technology	Taiwan
Jiajie	Fan	Fudan University	China
Yu-Wei	Fan	National University of Defense Technology	China
Runchen	Fang	Western Digital Technologies Inc	United States
Xiaosheng	Fang	Fudan University	China
Nasri	Faouzi	CRMN	Tunisia
Matteo	Farronato	Polytechnic University of Milan	Italy
Esmat	Farzana	Iowa State University	United States
Marco	Fattori	Eindhoven University of Technology	Netherlands
Franz	Faupel	Kiel University	Germany
Davide	Favero	University of Padua	Italy
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Seung Hee	Lee	Chunbuk National University	South Korea
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Wen	Li	Michigan State University	United States
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Ying	Li	Chinese Academy of Sciences	China
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Jing	Wan	GlobalFoundries Inc	United States
Qing	Wan	Nanjing University	China
Ce	Wang	Zhejiang University	China
Dawei	Wang	Arizona State University	United States
Da-Wei	Wang	Zhejiang University	China
Debo	Wang	Nanjing University of Posts and Telecommunications	China
Dejun	Wang	Dalian University of Technology	China
Fang	Wang	Shanghai Institute of Technical Physics	China
Fengyun	Wang	Qingdao University	China
Guilei	Wang	Institute of Microelectronics	China
Haizhu	Wang	Changchun University of Science and Technology	China
Hengyu	Wang	Zhejiang University	China
Huida	Wang	Tsinghua University	China
I-Ting	Wang	National Chiao Tung University	Taiwan
Jiangjing	Wang	Xi'an Jiaotong University	China
Jianxun	Wang	University of Electronic Science and Technology of China	China
Jie	Wang	Hangzhou Dianzi University	China
Jingshan	Wang	University of Notre Dame	United States
Jinshu	Wang	Beijing University of Technology	China
Kai	Wang	Southern University of Science and Technology	China
Lingfei	Wang	Institute of Microelectronics, Chinese Academy of Sciences	China
Maojun	Wang	Peking University	China
Meng	Wang	Southeast University	China
Miaomiao	Wang	IBM Research	United States
Mingxiang	Wang	Soochow University	China
Mingyi	Wang	Purdue University	United States
Panni	Wang	Georgia Institute of Technology	United States
Peng	Wang	Western Digital Corp	United States
Qi	Wang	Peking University	China
Renjie	Wang	McGill University	Canada
Ruidi	Wang	University of Electronic Science and Technology of China	China
Runsheng	Wang	Peking University	China
Shaodi	Wang	University of California, Los Angeles	United States
Wei	Wang	Jilin University	China

First Name	Last Name	Affiliation	Country
Wei	Wang	Peng Cheng Laboratory	China
Wei	Wang	Shanghai Industrial Technology Research Institute	China
Wei	Wang	University of Electronic Science and Technology of China	China
Weihua	Wang	Nankai University	China
Xiaolei	Wang	Institute of Microelectronics, Chinese Academy of Sciences	China
Xingsheng	Wang	Huazhong University of Science and Technology	China
Yan	Wang	Tsinghua University	China
Ying	Wang	Institute of Microelectronics	China
You	Wang	Nanjing University of Aeronautics and Astronautics	China
Yuan	Wang	Institute of Microelectronics	China
Yuhua	Wang	Lanzhou University	China
Yuru	Wang	Hong Kong University of Science and Technology	Hong Kong
Yu-Wu	Wang	National Changhua University of Education	Taiwan
Zegao	Wang	Aarhus Universitet	Denmark
Zeheng	Wang	University of New South Wales	Australia
Zheng	Wang	Georgia Institute of Technology	United States
Zheng	Wang	Micron Technology Inc	United States
Zhenxing	Wang	National Center for Nanoscience and Nanotechnology	China
Zheyao	Wang	Tsinghua University	China
ZhongQiang	Wang	Northeast Normal University	China
Zhongrui	Wang	University of Hong Kong	Hong Kong
Zixin	Wang	The University of Manchester	United Kingdom
Ziyu	Wang	University of Michigan	United States
Zongwei	Wang	Peking University	China
Zuankai	Wang	City University of Hong Kong	Hong Kong
Rainer	Waser	RWTH Aachen University	Germany
Tatsuro	Watahiki	Mitsubishi Electric Corporation	Japan
Atom	Watanabe	IBM T. J. Watson Research Center	United States
Naoki	Watanabe	Hitachi, Ltd.	Japan
Brandon	Weatherford	Stanford Linear Accelerator Center	United States
Thomas	Weatherley	École polytechnique fédérale de Lausanne (EPFL)	Switzerland
Jie	Wei	University of Electronic Science and Technology of China	China
Jin	Wei	Peking University	China
Ke	Wei	Institute of Microelectronics, Chinese Academy of Sciences	China
Lan	Wei	University of Waterloo	Canada
Tiwei	Wei	Purdue University	United States
Zhiqiang	Wei	Avalanche Technology Inc.	United States
Zhongming	Wei	Institute of Semiconductors, Chinese Academy of Sciences	China
Martin	Weis	Slovak University of Technology	Slovakia
Deqi	Wen	Michigan State University	United States
Haoran	Wen	Georgia Institute of Technology	United States
Jiaxuan	Wen	University of Minnesota	United States
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Hui-Yung	Wong	San Jose State University	United States
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First Name	Last Name	Affiliation	Country
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Heng	Wu	IBM	United States
Heng	Wu	Peking University	China
Huaqiang	Wu	Tsinghua University	China
Jixuan	Wu	Shandong University	China
Meng-Chyi	Wu	National Tsing Hua University	Taiwan
Ming-Hung	Wu	National Yang Ming Chiao Tung University	Taiwan
Peng	Wu	Massachusetts Institute of Technology	United States
Qingqing	Wu	Lancaster University	United Kingdom
Shin-Tson	Wu	University of Central Florida	United States
Tian-Li	Wu	National Yang Ming Chiao Tung University	Taiwan
Wei-Jing	Wu	Institute of Polymer Optoelectronic Materials and Devices	China
Wei-Min	Wu	National Chiao Tung University	Taiwan
Wengang	Wu	Peking University	China
Xiaohan	Wu	Fudan University	China
Yongle	Wu	Beijing University of Posts and Telecommunications	China
You-Lin	Wu	National Chi-Nan University	Taiwan
Yuh-Renn	Wu	National Taiwan University	Taiwan
Yung-Chun	Wu	National Tsing Hua University	Taiwan
Zewei	Wu	University of Electronic Science and Technology of China	China
Zhenhua	Wu	Institute of Microelectronics, Chinese Academy of Sciences	China
Zhenping	Wu	Beijing University of Posts and Telecommunications	China
Zhicheng	Wu	IMEC	Belgium
Joachim	Wuerfl	Ferdinand-Braun-Institut	Germany
Adi	Khakoni	ams-OSRAM AG	Austria
Congxin	Xia	Henan Normal University	China
Kejun	Xia	Taiwan Semiconductor Manufacturing Co Ltd	Taiwan
Yang	Xiang	IMEC	Belgium
Bing	Xiao	Xi'an Jiaotong University	China
Ming	Xiao	Virginia Polytechnic Institute and State University	United States
Renzhen	Xiao	Northwest Institute of Nuclear Technology	China
T. Patrick	Xiao	Sandia National Laboratories	United States
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Bin	Xie	Huazhong University of Science and Technology	China
Chao	Xie	Anhui University	China
Huikai	Xie	Beijing Institute of Technology	China
Jingyi	Xie	University of Washington	United States
Qingyun	Xie	Massachusetts Institute of Technology	United States
Sihan	Xie	Massachusetts Institute of Technology	United States
Jie	Xiong	University of Illinois at Urbana-Champaign	United States
Ying	Xiong	Southern University of Science and Technology	China
Chuan	Xu	Maxim Integrated	United States
Haoran	Xu	Los Alamos National Laboratory	United States
Jianjun	Xu	Keysight Technologies	United States
Jin-Xu	Xu	South China University of Technology	China
Ming	Xu	Xi'an Univerisy of Technolgoy	China
Shengrui	Xu	Xidian University	China
Wei	Xu	Shenzhen University	China
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Xiaoxin	Xu	Institute of Microelectronics, Chinese Academy of Sciences	China

<b>First Name</b>	<b>Last Name</b>	<b>Affiliation</b>	<b>Country</b>
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Dharmendra	Yadav	National Institute of Technology Hamirpur	India
Sachin	Yadav	IMEC	Belgium
Shailendra	Yadav	IIT Roorkee	India
Dmitry	Yakimets	IMEC	Belgium
Toshishige	Yamada	University of California Santa Cruz	United States
Yuusuke	Yamaguchi	University of Fukui	Japan
Dawei	Yan	Jiangnan University	China
Hao	Yan	National ASIC System Engineering Research Center	China
Lixin	Yan	Tsinghua University	China
Wei-Zhong	Yan	University of Electronic Science and Technology of China	China
Yong	Yan	Henan Normal University	China
Hanwu	Yang	National University of Defense Technology	China
Haozhang	Yang	Peking University	China
Joshua	Yang	University of Southern California	United States
Ling	Yang	Xidian University	China
Ning	Yang	University of Florida	United States
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S.	Yang	Tianjin University	China
Shengyi	Yang	Beijing Institute of Technology	China
Yansong	Yang	The Hong Kong University of Science and Technology	Hong Kong
Yuchao	Yang	Peking University	China
Junk	Yannik	Forschungszentrum Jülich GmbH	Germany
Ran	Yao	Chongqing University	China
Ri-Hui	Yao	South China University of Technology	China
Yixu	Yao	Chinese Academy of Sciences	China
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Luke	Yates	Sandia National Laboratories	United States
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Teng-Hao	Yeh	Macronix International Co. Ltd.	Taiwan
Cheng-Tyng	Yen	Hestia Power Inc.	Taiwan
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Bo	Yi	University of Electronic Science and Technology of China	China
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Hanbin	Ying	Georgia Institute of Technology	United States
Geonwook	Yoo	Soongsil University	South Korea
Seunghyup	Yoo	KAIST	South Korea
Jun-Sik	Yoon	POSTECH	South Korea
Sungmin	Yoon	Kyung Hee University	South Korea
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Eunseon	Yu	Purdue University	United States
Hao	Yu	IMEC	Belgium
Hengyu	Yu	Hunan University	China
Hongyu	Yu	Southern University of Science and Technology	China
Huihui	Yu	University of Science and Technology Beijing	China
Linwei	Yu	Nanjing University	China
Shimeng	Yu	Georgia Institute of Technology	United States
Wenjie	Yu	Shanghai Institute of Microsystem and Information Technology	China
Yuechuan	Yu	Analog Devices Inc	United States
Zhinong	Yu	-	China
Jiahui	Yuan	SanDisk	United States
Sining	Yun	Xi'an University of Architecture and Technology	China
Sabahattin	Yurt	Qualcomm Technologies Inc.	United States
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Cristian	Zambelli	University of Ferrara	Italy
Peter J.	Zampardi	Qorvo Inc	United States
Enrico	Zanoni	Università degli Studi di Padova	Italy
Tommaso	Zanotti	Università degli Studi di Modena e Reggio Emilia	Italy
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Vladislav	Zaslavsky	FSBSI Federal Research Center Institute of Applied Physics of the Russian Academy of Sciences	Russia
Michele	Zenari	Università degli Studi di Padova	Italy
Guang	Zeng	Infineon Technologies AG	Germany
Hui	Zeng	Nanjing University of Science and Technology	China
Jun	Zeng	MaxPower Semiconductor Inc	United States
Ke	Zeng	Stanford University	United States
Ke	Zeng	University at Buffalo	United States
Lang	Zeng	Beihang University	China
X-H	Zeng	Yangzhou University	China
Xiangbin	Zeng	Huazhong University of Science and Technology	China
Yujia	Zeng	Shenzhen University	China
Tianyou	Zhai	Huazhong University of Science and Technology	China
Anbang	Zhang	University of Electronic Science and Technology of China	China
Changqing	Zhang	Institute of Electronics, Chinese Academy of Sciences	China
Chaoqi	Zhang	Georgia Institute of Technology	United States
Dao	Zhang	Nanyang Technological University	Singapore
Dongli	Zhang	Soochow University	China
Dongzhi	Zhang	China University of Petroleum	China
Fujun	Zhang	Institute of Optoelectronic Technology	China
Gang	Zhang	A*STAR	Singapore
Guohe	Zhang	School of Microelectronics	China
Hong	Zhang	Chongqing Normal University	China
Hong	Zhang	Fudan University	China
Jian	Zhang	Liverpool John Moores University	United Kingdom
Jie	Zhang	Purdue University	United States
Jing	Zhang	Rochester Institute of Technology	United States
Lei	Zhang	NXP Semiconductors	United States
Liangliang	Zhang	Stanford University	United States
Ling Qian	Zhang	Institute of Microelectronics, Chinese Academy of Sciences	China
Lining	Zhang	Peking University	China

First Name	Last Name	Affiliation	Country
Lining	Zhang	Shenzhen University	China
Long	Zhang	Southeast University	China
Meng	Zhang	Shenzhen University	China
Panpan	Zhang	Beijing University of Posts and Telecommunications	China
Peng	Zhang	Michigan State University	United States
Rui	Zhang	Zhejiang University	China
Shengdong	Zhang	Peking University	China
Shengli	Zhang	Nanjing University of Science and Technology	China
Teng	Zhang	Peking University	China
Wei	Zhang	Liverpool John Moores University	United Kingdom
Wei	Zhang	Xi'an Jiaotong University	China
Wentong	Zhang	University of Electronic Science and Technology of China	China
Xue	Zhang	Xiangtan University	China
Xufang	Zhang	Tsukuba Daigaku	Japan
Yi	Zhang	Nankai University	China
Yong	Zhang	University of North Carolina at Charlotte	United States
Yongai	Zhang	Fuzhou University	China
Yongzhe	Zhang	Beijing University of Technology	China
Yu	Zhang	Sun Yat-Sen University	China
Yue	Zhang	Beihang University	China
Yuewei	Zhang	University of California, Santa Barbara	United States
Yuhao	Zhang	Virginia Polytechnic Institute and State University	United States
Zexuan	Zhang	Cornell University	United States
Zhaofu	Zhang	Cambridge University	United Kingdom
Zhaohao	Zhang	Institute of Microelectronics, Chinese Academy of Sciences	China
Zhiyong	Zhang	Peking University	China
Zicheng	Zhang	National University of Defense Technology	China
Zi-Hui	Zhang	Hebei University of Technology	China
Ziyue	Zhang	Beijing Institute of Technology	China
Chun	Zhao	Xi'an Jiaotong-Liverpool University	China
Ding	Zhao	Institute of Electronics, Chinese Academy of Sciences	China
Feng	Zhao	Washington State University	United States
Junping	Zhao	Xi'an Jiaotong University	China
Rong	Zhao	Xidian University	China
Shenglei	Zhao	Xidian University	China
Songrui	Zhao	McGill University	Canada
Weisheng	Zhao	Beihang University	China
Wen-Sheng	Zhao	Hangzhou Dianzi University	China
Yi	Zhao	Zhejiang University	China
Yiying	Zhao	China Academy of Engineering Physics	China
Yuanfu	Zhao	Beijing Microelectronics Technology Institute	China
Yudi	Zhao	Peking University	China
Dongqi	Zheng	Apple Inc	United States
Huai	Zheng	Wuhan University	China
Limei	Zheng	Shandong University	China
Wei	Zheng	Sun Yat-Sen University	China
Xiao-Hong	Zheng	Institute of Solid State Physics Chinese Academy of Sciences	China
Xin	Zheng	Stanford University	United States
Xuefeng	Zheng	Xidian University	China
Yuan	Zheng	University of California Davis	United States
Yuan	Zheng	University of Electronic Science and Technology of China	China
Zheyang	Zheng	Hong Kong University of Science and Technology	Hong Kong
Zhi-Wei	Zheng	Xiamen University	China



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Hong	Zhou	Xidian University	China
Jian	Zhou	Hunan University	China
Jingan	Zhou	Rice University	United States
Jiuren	Zhou	Xidian University	China
Liang	Zhou	Shanghai Jiao Tong University	China
Otto	Zhou	University of North Carolina at Chapel Hill	United States
Wei	Zhou	Hong Kong University of Science and Technology	Hong Kong
Xin	Zhou	University of Electronic Science and Technology of China	China
Xingye	Zhou	Hebei Semiconductor Research Institute	China
Xintian	Zhou	Beijing University of Technology	China
Yan-Guang	Zhou	The Hong Kong University of Science and Technology	Hong Kong
Ye	Zhou	Shenzhen University	China
Yichun	Zhou	Xiangtan University	China
Yuanzhong	Zhou	Analog Devices Inc	United States
Yugang	Zhou	Nanjing University	China
Zheng	Zhou	China Academy of Engineering Physics	China
Zheng	Zhou	Peking University	China
Zusheng	Zhou	Institute of High Energy Physics, Chinese Academy of Sciences	China
Chunxiang	Zhu	National University of Singapore	Singapore
He	Zhu	University of Technology Sydney	Australia
Jiejie	Zhu	Xidian University	China
Lei	Zhu	University of Macau	Macao
Maguang	Zhu	Peking University	China
Peifen	Zhu	University of Missouri	United States
Xi	Zhu	University of Technology Sydney	Australia
Yuanwei	Zhu	Xi'an Jiaotong University	China
Jia	Zhuang	Stanford University	United States
Fei	Zhuge	Ningbo Institute of Materials Technology and Engineering Chinese Academy of Sciences	China
Nouman	Zia	Tampere University of Technology	Finland
Thomas	Zimmer	Université de Bordeaux	France
Cezar	Zota	IBM Zurich Research Laboratory	Switzerland
Xiao	Zou	Jiangnan University	China
Ahmad	Zubair	Bangladesh University of Engineering and technology	Bangladesh
Ahmad	Zubair	Intel Corporation	United States
Muhammed	Zuboraj	Los Alamos National Laboratory	United States